

Amendments to the Specification:

Please replace the paragraph on page 10, line 21 to page 11, line 3 with the following:

A solvent is utilized to modify the viscosity of the composition. Preferably, the solvent will evaporate during the B-stage process which occurs at temperatures lower than about 150° C. Common solvents that readily dissolve the epoxy resins, are non-reactive and have the proper boiling point ranging from 100° C to 200° C are preferable for use with this application. Examples of solvents that may be utilized include ketones, esters, alcohols, ethers, and other common solvents that are stable and dissolve the epoxy and phenolic resins in the composition. Preferred solvents include γ -butyrolactone and propylene glycol methyl ethyl acetate (PGMEA).